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KC ČIP.SI
SLOVENSKI KOMPETENČNI
CENTER ZA ČIPE

NOVIČNIK

Petek, 27. februar 2026

Pozdravljeni,

pošiljamo vam pregled izbranih informacij in novosti s področja čipov, polprevodnikov ter aktivnosti KC Čip.si.

Aktualno

- **Poziv : Call for Mentors, Experts & Keynote Speakers for the EuroCDP Program**
  EuroCDP objavlja evropski poziv za strokovnjake iz industrije, tehnične eksperte, vodilne kadre, ustanovitelje, investitorje in izkušene praktike, ki želijo soustvarjati novo generacijo evropskih podjetij za načrtovanje integriranih vezij.
- **Delavnica: 2D Materials for Future Electronics**
  3. marec 2026, 16:50-18:05 CET, hibridna izvedba
  Delavnica bo v družbi vodilnih raziskovalcev in strokovnjakov iz industrije obravnavala najnovejše dosežke ter prihodnje priložnosti na področju elektronskih aplikacij
- **Usposabljanje: FIDES Methodologz and Tool Training**
  20.-21. april 2026 in 23.-24. april 2026, Louvain-la-Neuve, Belgijia, on-site
  Sistemski inženirji, inženirji ali raziskovalci, ki želijo pridobiti znanje vodilnih strokovnjakov iz industrije o vidikih zanesljivosti v sistemskem inženirstvu.
- **Webminar: Building the Future Together: Integrating Sustainability in the Semiconductor Ecosystem**
  15. april 2026, 13:00-14:30, on-line
  Webminar on one of the semiconductor industry's key sustainability challenges: replacing PFAS and the skills needed to make it happen.

Zanimivosti s področja:

- **Chips to cut AI energy use being developed by European and South Korean scientists**
  With the 3-year long Horizon Chis JU project HAETAE, a team of researchers from Europe and South Korea is using photonics to cut the energy cost of AI and strengthen cybersecurity for future digital services.
- **ASML makes breakthrough in EUV chipmaking tech, plans to increase speed by 50% by 2030 — new 1,000-watt light source fires three lasers at 100,000 tin droplets every second**
  A 1,000-W EUV source fires three lasers at 100,000 tin droplets per second, enabling up to 330 wafers/hour and significantly lowering cost per wafer.

- **[New chip-fabrication method creates 'twin' fingerprints for direct authentication]**
  Engineers can leverage this unforgeable ID for authentication, to safeguard a device from attackers trying to steal private data
- **[China to increase leading-edge chip output by 5x in two years]**
  The aim is to lift 7nm and 5nm production to 100,000 wafers per month, targeting half a million monthly by 2030.
- **[Designing the Future: AI-Driven Multi-Die Innovation in the Era of Agentic Engineering]**
  A bold vision for the future of semiconductor innovation: AI-driven multi-die design powered by agentic intelligence.
- **[AI Starting To Simplify Design Of Programmable Logic]**
  AI is beginning to make inroads into designing and managing programmable logic.
- **[Chipmakers still suffering from rare earth shortages]**
  Some suppliers have even rejected taking on new clients because of limited inventories.
- **[AI Starting To Simplify Design Of Programmable Logic]**
  AI/ML speed up FPGA design, higher-level languages could improve compilers, and ML can auto-tune DSP algorithms from analog simulations.

Lep pozdrav,

vaš KC Čip.si

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SLOVENSKI KOMPETENČNI
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Slovenski kompetenčni center za čipe in polprevodniške tehnologije

KC Čip.si - glavna pisarna

Fakulteta za elektrotehniko, Univerza v Ljubljani

Tržaška cesta 25,Ljubljana

E-pošta: office@cc-chip.si

Tel.: 01 476 88 50

Spletna stran (v izdelavi): https://cc-chip.si/

Financira
Evropska unija

REPUBLIKA SLOVENIJA
MINISTRSTVO ZA DIGITALNO PREOBRAZBO

Projekt CC Chip.si (št. 101217674) je sofinanciran s strani Chips Joint Undertaking in Evropske unije v okviru programa Digital Europe.
